

REMARKS

Request for Withdrawal of the Finality of the Office Action mailed June 2, 2005

The applicant requests, in accordance with MPEP 706.07(d), withdrawal of the finality of the Office Action mailed on June 2, 2005 as being premature. A second or any subsequent action on the merits should *not* be made final if it includes a rejection, on prior art not of record, of any claim amended to include limitations *which should reasonably have been expected to be claimed*. MPEP 706.07(a), emphasis added.

The final office action mailed on June 2, 2005 rejects claim 55 based on U.S. Patent No. 6,198,171 to Huang, et al. ("Huang") and JP-05-144869 to Noriyuki ("Noriyuki"), both of which are newly cited art.

In the response to the non-Final Office Action that was mailed on November 18, 2004, claim 55 was amended to more clearly and plainly recite the features of the claim. For illustration, the amendments that were made to claim 55 are repeated below.

1 55. (Currently amended) An ultra-thin semiconductor package device comprising:
2 a lead frame comprising that includes a die pad having a uniform first thickness, a
3 plurality of leads disposed around the die pad, and tie bars connected to and disposed around
4 the die pad, wherein said the die pad comprises including a chip attaching part and a
5 peripheral part surrounding the chip attaching part;
6 a semiconductor chip mounted to the die pad chip attaching part, said the
7 semiconductor chip having a plurality of electrode pads, wherein each of the plurality of
8 electrode pads is directly coupled to a corresponding lead with a bonding wire, and wherein
9 each of the leads comprises integrally connected inner leads and outer leads;
10 an encapsulant encapsulating a package body that encapsulates the semiconductor
11 chip, the die pad, the bonding wires, and a portion of the leads to define inner leads that are
12 disposed inside the package body and outer leads that are disposed outside the package body,
13 the inner leads having a uniform second thickness that is greater than the first thickness, to
14 form a package body, wherein said inner leads are encapsulated by the encapsulant and said
15 outer leads are external to the encapsulant, and
16 said chip attaching part having a first thickness and the inner leads totally having a
17 constant second thickness greater than the first thickness, wherein the chip attaching part and
18 the peripheral part have the same thickness.

In line 2 of the claim, it is reasonable to expect that "comprising" might be replaced with the synonymous phrase "that includes." Furthermore, it is reasonable to expect that the feature of a die pad "having a uniform first thickness" could be added to the claim, since lines 4 and 5 indicate that the die pad includes a chip attaching part and a peripheral part, line 16 indicated that the chip attaching part has a first thickness, and lines 17-18 indicated that the chip attaching part and the peripheral part have the same thickness.

In line 3 of the claim, the use of "leads" rather than "a plurality of leads" can reasonably have been expected.

In line 4 of the claim, it is reasonable to expect that "wherein said" could alternatively be stated as "the" and that "comprises" could alternatively be stated as "including."

In line 6 of the claim, it is reasonable to expect that the semiconductor chip could be mounted to the chip attaching part rather than the die pad, because, after all, it was previously stated in line 4 that the die pad included a chip attaching part. Furthermore, the very name "chip attaching part" indicates that this is the part of the die pad that is used to attach the chip.

In line 7, it is reasonable to expect that the terms "a plurality of," "wherein," and "plurality of" could be safely removed without affecting the scope of the claim.

In line 8, it reasonable to expect that each of the electrode pads might be "directly" coupled to a corresponding lead with a bonding wire, since allowed claim 71 already recites that "the bonding wires are directly connected to the portion of the inner leads."

In line 10, it could reasonably be expected that, since an encapsulant was originally recited as encapsulating the semiconductor chip "to form a package body" (lines 13-14), the package body could alternatively be said to encapsulate the semiconductor chip.

Furthermore, since the inner leads were originally defined as being encapsulated by the encapsulant (line 14) and the outer leads as being external to the encapsulant (line 15), it is reasonable to alternatively state that the package body encloses a portion of the leads (line 12) to define inner leads disposed inside the package body (lines 11-12) and outer leads disposed outside the package body (line 12).

It is also reasonable to state that the package body encapsulates the die pad and the bonding wires (line 11), because it was already been stated that the semiconductor chip is mounted to the chip attaching part of the die pad (lines 4-6) and that the electrode pads of the semiconductor chip are coupled to a corresponding lead with a bonding wire (lines 7-8). Thus, it is apparent that the die pad and the bonding wires are also encapsulated by the package body.

Finally, in line 13, it is reasonable to state that the inner leads have a uniform second thickness that is greater than the first thickness, since this aspect was originally recited in lines 16-17 ("the inner leads totally having a constant second thickness greater than the first thickness").

Conclusion

Since all the amendments previously made to claim 55 could reasonably have been expected, the finality of the Office Action mailed on June 2, 2005 should be withdrawn. Please telephone the undersigned at (503) 222-3613 if it appears that an interview would be helpful in advancing the case.

Respectfully submitted,

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